

SWS08C06L03 Data Sheet

Description

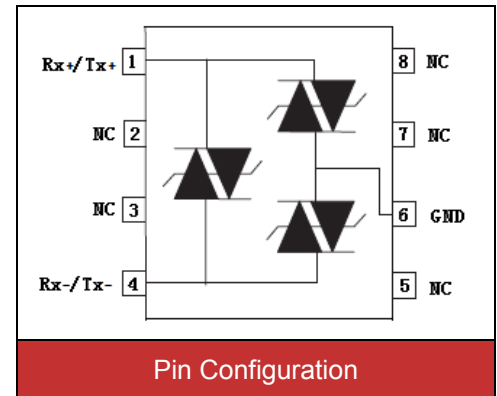
SWS08C06L03 is a low voltage transient surge absorbing device, it is mainly used to protect sensitive communications equipment from lightning and other transient phenomenon

Features

- SOIC-08 surface mount package
- Protects three high speed data lines
- Working voltage:6V
- Lead Free/ROHS compliant

Applications

- XDSL transmission equipment
- Data cable
- T1/E1 transmission protection
- Ethernet transmission protection



Maximum Ratings

Parameter	Symbol	Value	Unit
Peak Pulse Current(10/1000us)	I_{PP}	45	A
Peak Pulse voltage(10/700us)	V_{PP}	3000	V
Operating Junction Temperature	T_J	-40 to +150	°C
Storage Temperature Range	T_S	-40 to +150	°C
Junction to Ambient on printed circuit	$R_{\theta JA}$	170	°C/W

Electrical Characteristics($T_J=25^{\circ}C$)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	V_{RWM}				6	V
Breakover voltage	V_{BO}	1KV/ μ s			15	V
On-state Voltage	V_T	$I_T=2.2A$			4	V
Reverse leakage current	I_R	$V_R=6V$			5	μ A
Holding Current	I_H	10A, 10/1000 μ s		10		mA
Off state capacitance	C_O	1Vdc,f=1MHz,2Vbias		50		pF

Characteristics Curves

Figure 1. V-I Characteristics

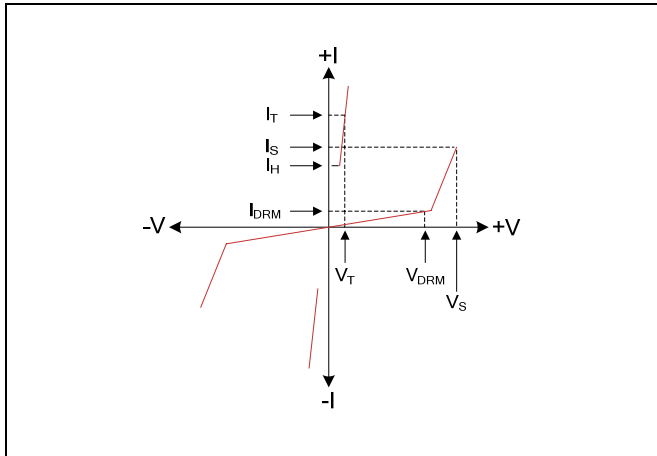
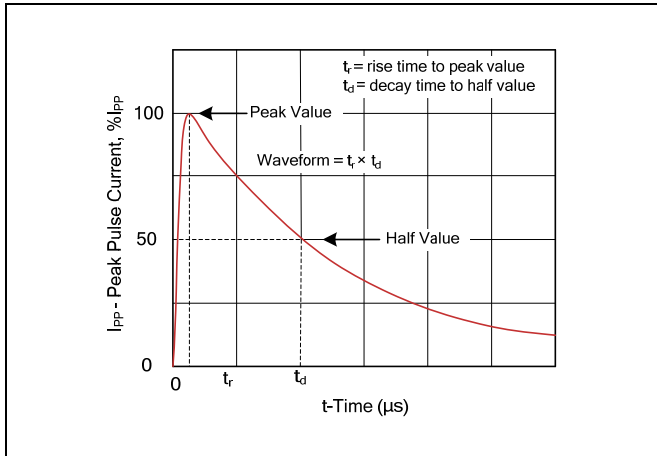
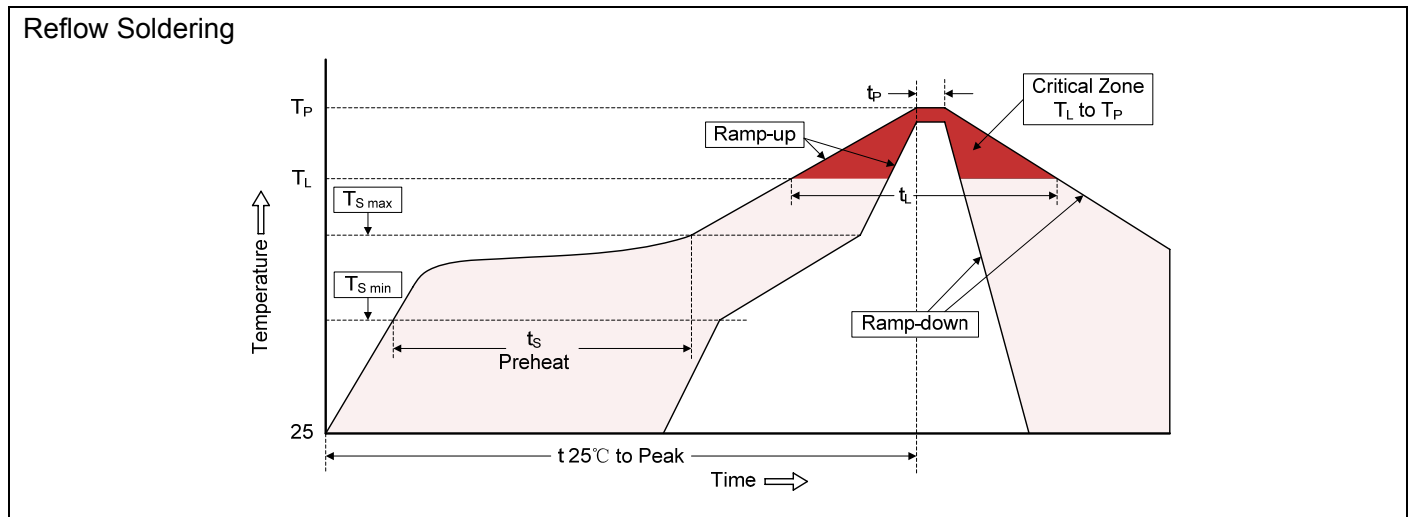


Figure 2. $t_r \times t_d$ Pulse Wave-form



Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat	
-Temperature Min ($T_{S\ min}$)	150°C
-Temperature Max ($T_{S\ max}$)	200°C
-Time (min to max) (t_s)	60-180 seconds
$T_{S\ max}$ to T_L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T_L)	217°C
-Time (t_L)	60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Dimensions (SOIC-08)

Symbol	Dimension			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.80	5.00	0.189	0.197
B	5.80	6.20	0.228	0.244
C	3.80	4.00	0.150	0.157
D	1.27		0.050	
E	0.33	0.51	0.013	0.020
F	0.40	1.27	0.016	0.050
G	0.19	0.25	0.007	0.010
H	1.35	1.75	0.053	0.069
H1	0.10	0.25	0.004	0.010
H2	1.45		0.057	

Recommended Soldering Pad Layout

Packaging

Tape	Symbol	Dimension(mm)
	W	12.00±0.30
P0	4.00±0.10	
P1	8.00±0.10	
P2	2.00±0.10	
D0	Φ1.55±0.10	
D1	Φ1.55±0.05	
E	1.75±0.10	
F	5.50±0.10	
A	6.50±0.10	
B	5.40±0.10	
K	2.00±0.10	
t	0.30±0.05	
Reel	D	Φ330.0±3.0
	D2	Φ13.0
	W1	13.5
		Quantity: 2500PCS